L Number	Hits	Search Text	DB	Time stamp
-	28022	etchant or "etching gas"	USPAT; US-PGPUB	2002/12/17 18:10
-	145	(adsorb$3 or adsorption or condens$3 or condensation) with (etchant or "etching gas")	USPAT; US-PGPUB	2002/12/17 21:18
-	994349	water	USPAT; US-PGPUB	2002/12/17 21:18
-	21966	ozone and water	USPAT; US-PGPUB	2002/12/17 21:18
-	10405	(adsorb$3 or adsorption or condens$3 or condensation) and (ozone and water)	USPAT; US-PGPUB	2002/12/17 21:19
-	215	(etchant or "etching gas") and ((adsorb$3 or adsorption or condens$3 or condensation) and (ozone and water))	USPAT; US-PGPUB	2002/12/17 21:19
-	553830	semiconductor or "integrated circuit" or silicon	USPAT; US-PGPUB	2002/12/17 21:20
-	3533	((adsorb$3 or adsorption or condens$3 or condensation) and (ozone and water)) and (semiconductor or "integrated circuit" or silicon)	USPAT; US-PGPUB	2002/12/17 21:21
-	200	(adsorb$3 or adsorption or condens$3 or condensation) with ozone with water	USPAT; US-PGPUB	2002/12/17 21:21
-	15	(US-6337277-$ or US-6099945-$ or US-6024888-$ or US-5935454-$ or US-5500079-$ or US-5354416-$ or US-5087323-$ or US-5030319-$ or US-6299696-$).did. or (US-20020177323-$ or US-20020121502-$ or US-20020038681-$ or US-20010006849-$ or US-20020134409-$ or US-20020122753-$).did.	USPAT; US-PGPUB	2002/12/18 12:25
-	490771	wafer or substrate	USPAT; US-PGPUB	2002/12/18 12:26
-	700153	cool$3	USPAT; US-PGPUB	2002/12/18 12:26
-	22000	(wafer or substrate) with cool$3	USPAT; US-PGPUB	2002/12/18 12:27
-	29628	ozone	USPAT; US-PGPUB	2002/12/18 12:27
-	828	((wafer or substrate) with cool$3) and ozone	USPAT; US-PGPUB	2002/12/18 12:27
-	347653	@ad>20000523 @rlad>20000523	USPAT; US-PGPUB	2002/12/18 12:28
-	649	(((wafer or substrate) with cool$3) and ozone) not (@ad>20000523 @rlad>20000523)	USPAT; US-PGPUB	2002/12/18 12:28
-	1021500	water or steam	USPAT; US-PGPUB	2002/12/18 12:29
-	486	((((wafer or substrate) with cool$3) and ozone) not (@ad>20000523 @rlad>20000523)) and (water or steam)	USPAT; US-PGPUB	2002/12/18 12:29
-	392087	adsorb$3 or adsorption or condens$3 or condensation	USPAT; US-PGPUB	2002/12/18 12:30
-	289	(((((wafer or substrate) with cool$3) and ozone) not (@ad>20000523 @rlad>20000523)) and (water or steam)) and (adsorb$3 or adsorption or condens$3 or condensation)	USPAT; US-PGPUB	2002/12/18 12:30
-	52	(semiconductor or "integrated circuit" or silicon) and ((adsorb$3 or adsorption or condens$3 or condensation) with ozone with water)	USPAT; US-PGPUB	2002/12/18 15:18
-	288	((((((wafer or substrate) with cool$3) and ozone) not (@ad>20000523 @rlad>20000523)) and (water or steam)) and (adsorb$3 or adsorption or condens$3 or condensation)) not ((semiconductor or "integrated circuit" or silicon) and ((adsorb$3 or adsorption or condens$3 or condensation) with ozone with water))	USPAT; US-PGPUB	2002/12/18 12:31
-	35	(semiconductor or "integrated circuit" or silicon) and ((adsorb$3 or adsorption or condens$3 or condensation) and ozone and water)	EPO; JPO; DERWENT; IBM_TDB	2002/12/18 15:19

-	12	(semiconductor or "integrated circuit" or silicon) and ((adsorb$3 or adsorption or condens$3 or condensation) with ozone with water)	EPO; JPO; DERWENT; IBM_TDB	2002/12/18 15:22
-	23	((semiconductor or "integrated circuit" or silicon) and ((adsorb$3 or adsorption or condens$3 or condensation) and ozone and water)) not ((semiconductor or "integrated circuit" or silicon) and ((adsorb$3 or adsorption or condens$3 or condensation) with ozone with water))	EPO; JPO; DERWENT; IBM_TDB	2002/12/18 15:22
-	71	(US-6337277-$ or US-6099945-$ or US-6024888-$ or US-5935454-$ or US-5500079-$ or US-5354416-$ or US-5087323-$ or US-5030319-$ or US-6299696-$ or US-6432845-$ or US-6429493-$ or US-6403498-$ or US-6368891-$ or US-6358830-$ or US-6350685-$ or US-6340435-$ or US-6284205-$ or US-6281141-$ or US-6246105-$ or US-6245659-$ or US-6239041-$ or US-6238511-$ or US-6232156-$ or US-6194304-$ or US-6184068-$ or US-6144097-$).did. or (US-6143081-$ or US-6107182-$ or US-5967156-$ or US-5962194-$ or US-5953634-$ or US-5925577-$ or US-5923962-$ or US-5904770-$ or US-5843833-$ or US-5840600-$ or US-5714306-$ or US-5643826-$ or US-5078832-$ or US-4911103-$ or US-4910043-$ or US-4906328-$ or US-4891488-$ or US-4886570-$ or US-4877757-$ or US-4875989-$ or US-4863558-$ or US-4857132-$ or US-4855160-$ or US-4844773-$ or US-4842687-$ or US-4842676-$ or US-4836905-$).did. or (US-4832779-$ or US-4832777-$ or US-4830705-$ or US-4830700-$ or US-4822450-$ or US-4818327-$ or US-4818326-$ or US-4778532-$).did. or (US-20020177323-$ or US-20020121502-$ or US-20020038681-$ or US-20010006849-$ or US-20020134409-$ or US-20020122753-$).did. or (JP-2001276758-$ or US-20020050279-$ or US-20020020436-$ or WO-200137329-$).did.	USPAT; US-PGPUB; DERWENT	2002/12/18 17:38
-	1	("6240933").PN.	USPAT; US-PGPUB	2002/12/18 17:38